

Done with help of Tilman and Silvan on Dec 19  
ROC wafer: X74TLAT  
Sensor ID: 8284-12 (batch-wafer)

Sensor 14, ROC 47A

1. Row:Col - 76:49-50; 77:48-50; 78:48-50
  2. Row:Col - 11:47-48; 12:47-48
  3. Row:Col - 44:26-27; 45:26-27; 46:26-27
  4. 'touched' corner: 75-79:43-51
- Pictures: 2-1-3 (in order in the folder)

Sensor 13, ROC 46A

1. Row:Col - 70:4-6; 71:4,6; 72:4-6
  2. Row:Col - 69-74:34-35; 69-70:36
- Pictures: 1-2

Was reworked due to after first bonding Si and ROC were split apart  
(2) have small bumps in top corners

Sensor 11, ROC 49A

1. Row:Col - 27-30:37-38
  2. Row:Col - 68-69:9-10
- Pictures: 1-2

Sensor 10, ROC 48B

1. Row:Col - 64-65:37-38
  2. Row:Col - 64-65:31-33
  3. Row:Col - 32:13-15; 33:11-13; 34:11-12
- Pictures: 1-2-3

(2) has

- 1 large bump: right column, 3 from top
- 3 small bumps: left column, 2-4 from top
- 1 very small bump: right column, at the bottom
- may be a contact between 2 pixels in but last raw, leftest

Pattern of (2):

```
0 . .  
0 o .  
0 o O  
0 o .  
x . .  
. . s
```

0 - normal bump; o - small (leftover) bump, O - large (leftover) bump, x - 2 bumps contact(?), s - very small bump